



Lead Free and RoHS Compliant

Analog Express certifies that our Pb-Free die/wafer and other components such as epoxy resin, lead-frame, die attach and solder are manufactured under the Lead Free Program and are in compliance with the European Union Directive 2002/95/EC (RoHS Directive).

Analog Express integrated circuit components have been identified as RoHS compliant and do not exceed the maximum for the following 6 designated substances.

Main Substance: Silicon Wafer

Substance	RoHS Limit (ppm)
Cadmium (Cd)	100
Lead (Pb)	1000
Mercury (Hg)	1000
Hexavalent Chromium (CrVI)	1000
Poly Brominated Biphenyls (PBBs)	1000
Poly Brominated Diphenyl Ethers (PBDE)	1000

Main Substance: IC Packaging (Epoxy Resin, Die Attach Epoxy, Bond Wire and Lead-frame)

Substance	RoHS Limit (ppm)
Cadmium (Cd)	100
Lead (Pb)	1000
Mercury (Hg)	1000
Hexavalent Chromium (CrVI)	1000
Poly Brominated Biphenyls (PBBs)	1000
Poly Brominated Diphenyl Ethers (PBDE)	1000

Contacts

For any question or inquiry regarding this document, please email to quality@analogexpress.com.
RoHS test reports are available upon request.